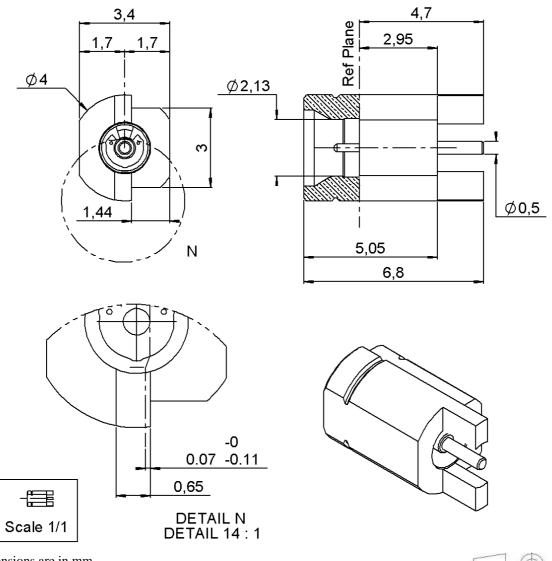
R201.423.110

Series : **SMPM**

FULL DETENT-TAPE AND REEL BY 500



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	BERYLLIUM COPPER BERYLLIUM COPPER PEEK	GOLD 0.5 OVER NICKEL 2 GOLD 0.5 OVER NICKEL 2
-	-	-

Issue: 1349

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



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PACKAGING

Unit Other 'W' option Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance **50** Ω

Frequency **0-40** GHz

VSWR 1.3* + **0.0000** x F(GHz) Maxi Insertion loss .12** $\sqrt{F(GHz)}$ dB Maxi

TBD - F(GHz)) dB Maxi RF leakage

Voltage rating 335 Veff Maxi Dielectric withstanding voltage 500 Veff mini

Insulation resistance **5000** MΩ mini

ENVIRONMENTAL

-65/+165 ° C Operating temperature

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHER CHARACTERISTICS

Assembly instruction NA

Others:

*VSWR: 1.10(DC~26.5GHz);1.3(26.5~40GHz)

**Coaxial transmission line only

MECHANICAL CHARACTERISTICS

Center contact retention

Standard

500

Axial force – Mating end **6.7** N mini Axial force – Opposite end **6.7** N mini Torque NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 100 Cycles mini

Weight **0,3500** g

Issue: 1349

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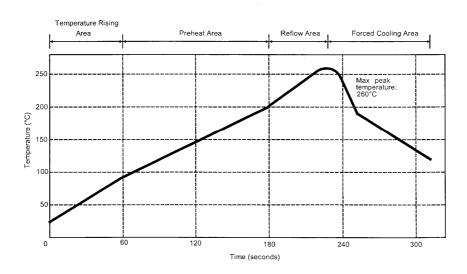
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SOLDER PROCEDURE

- 1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 μ m. Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component . Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged .
- 5. Verification of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

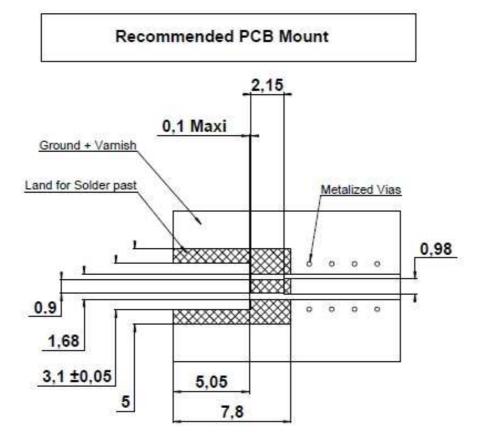
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Dimensions applicable for Roger RO4350 PCB material thickness 0.508 mm , with ground layer on bottom . Applicable Frequency - DC to 12Ghz

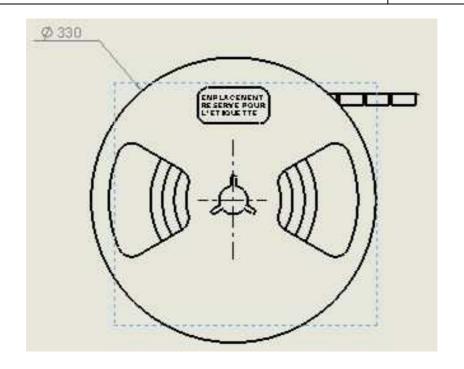
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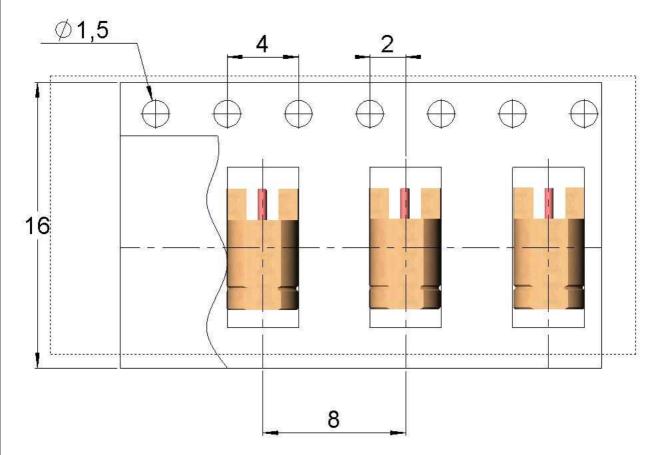


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Series : **SMPM**





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